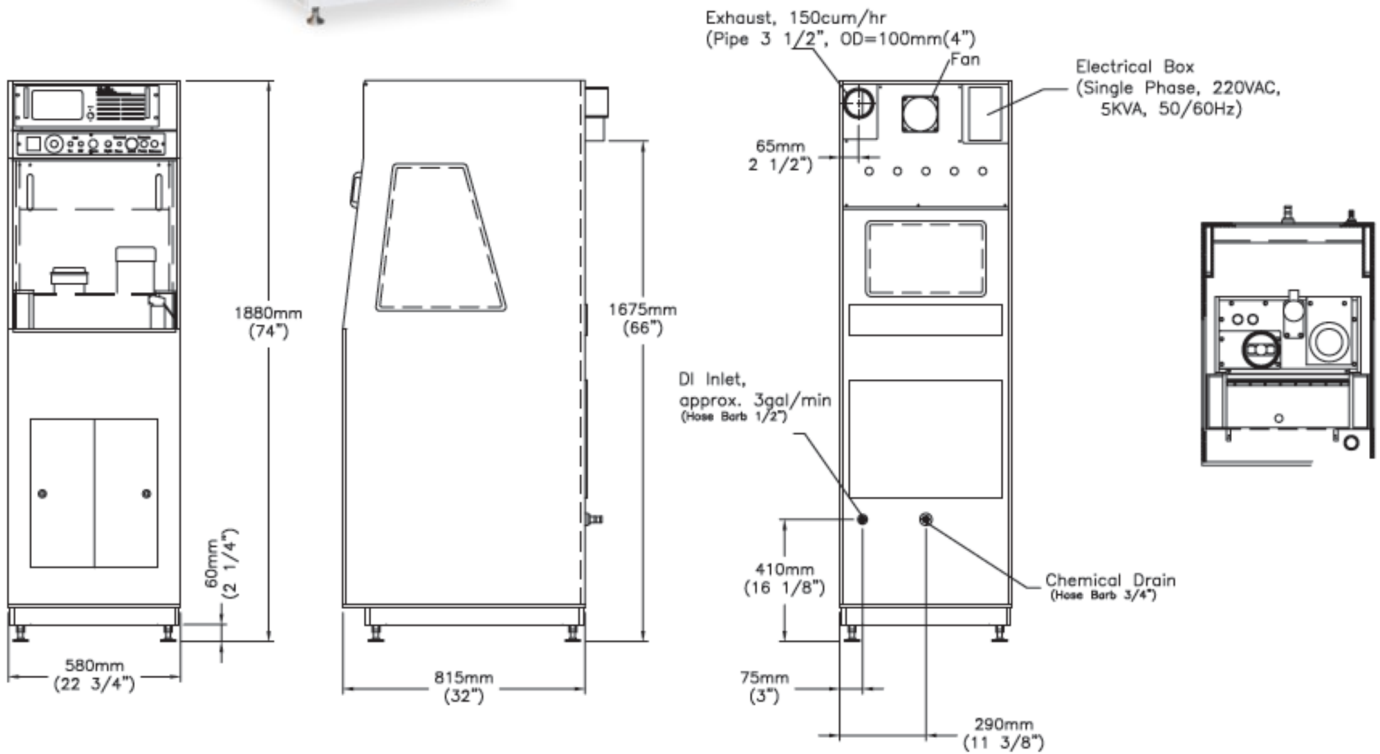


SE-101 Shim Electroforming/Electroplating System



Features

- Compact single cell design
- High flow rate
- Efficient filtration
- Easy process maintenance
- Precision microprocessor control
- Clean room compatible
- PC interface available
- Ni, Ni Alloy, Cu and other plating process options
- Precise control of thickness uniformity
- Easy operator interface
- All digital control system



SE-101 Shim Electroforming/Electroplating System

Specifications

Construction:	Polypropylene	
Dimensions:	Width	23" (580mm)
	Height	74" (1880mm)
	Depth	32" (815mm)
Shim Dimension Standard:		
	Max Shim Size:	300 x 300mm
	Max Wafer Size:	300mm
Total Solution Volume:	23 gal. (88 liters)	
Heaters:	2 kW	
Cooling:	Titanium cooling coil	
Cells:	1	
Pump:	3/4 hp	
Rectifier:	Standard	65 Amps 24 VDC
	Optional	Reverse pulse plating (specify range)
Filtration:	1 Stage, 0.5 to 5 micron DOE 20"	
Flow:	50-lpm max (adjustable)	
Instrumentation:	Temperature Controller: ± 1 degree C, dual setpoint	
Utilities:	Electrical	220VAC, 1 Phase, 5kVA, 50/60Hz
	DI Water Inlet:	Hose Barb 1/2" NPT Male, 11 lpm
	Cooling:	11 lph, Pressure 45-60 psi, Temp. = 12°C (52°F)


Front View

Side View

Rear View

Plating Cell